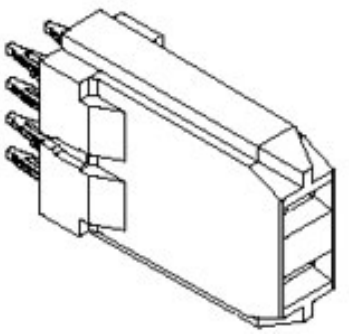
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Part Number: 0740298400
Status: Active
Overview: vhdm
Description: 2.00mm (.079") Pitch VHDM® Board-to-Board Backplane Receptacle Power Module, Vertical, 8-Row, 2 Circuits, Pin 2 Voided, Gold (Au) Selective 0.76µm (30µ")



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Packaging Specification (PDF)
Product Specification PS-74031-999 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

UL	E29179

General

Product Family	Backplane Connectors
Series	74029
Application	Backplane
Application Tooling Documents	Tooling Manual
Comments	Backplane Receptacle Module, Power
Component Type	Power Receptacle
Overview	vhdm
Product Name	VHDM®
Style	N/A

Physical

Circuits (Loaded)	2
Circuits (maximum)	3
Circuits Detail	Pin 2 voided
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Number of Columns	N/A
Number of Pairs	Open Pin Field
Number of Rows	8
Orientation	Vertical
PC Tail Length (in)	0.110 In
PC Tail Length (mm)	2.80 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.070 In
PCB Thickness Recommended (mm)	1.80 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.157 In
Pitch - Term. Interface (mm)	4.00 mm
Plating min: Mating (µin)	30

EU RoHS RoHS Compliant by Exemption
China RoHS 50 Pb
REACH SVHC Contains SVHC: No
Halogen-Free Status Halogen-Free

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
74029Series

Mates With
74026 VHDM® Board-to-Board Daughtercard Receptacle

Application Tooling | **FAQ**

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
VHDM® Backplane 6 and 8 Row Power Module Insertion Tool	0622020211

Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.375
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

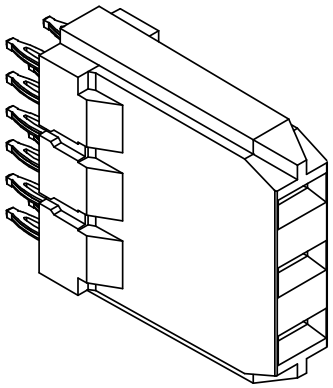
Current - Maximum per Contact	10A
Data Rate	2.5 Gbps
Real Signals (per 25mm)	100
Shielded	No
Voltage - Maximum	250V

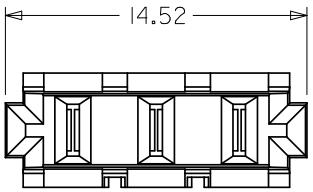
Material Info

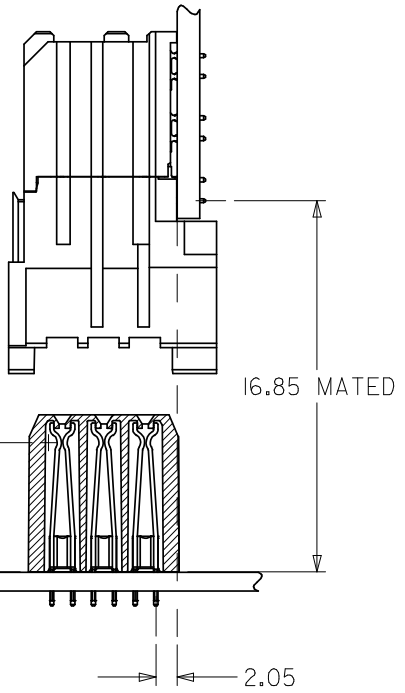
Reference - Drawing Numbers

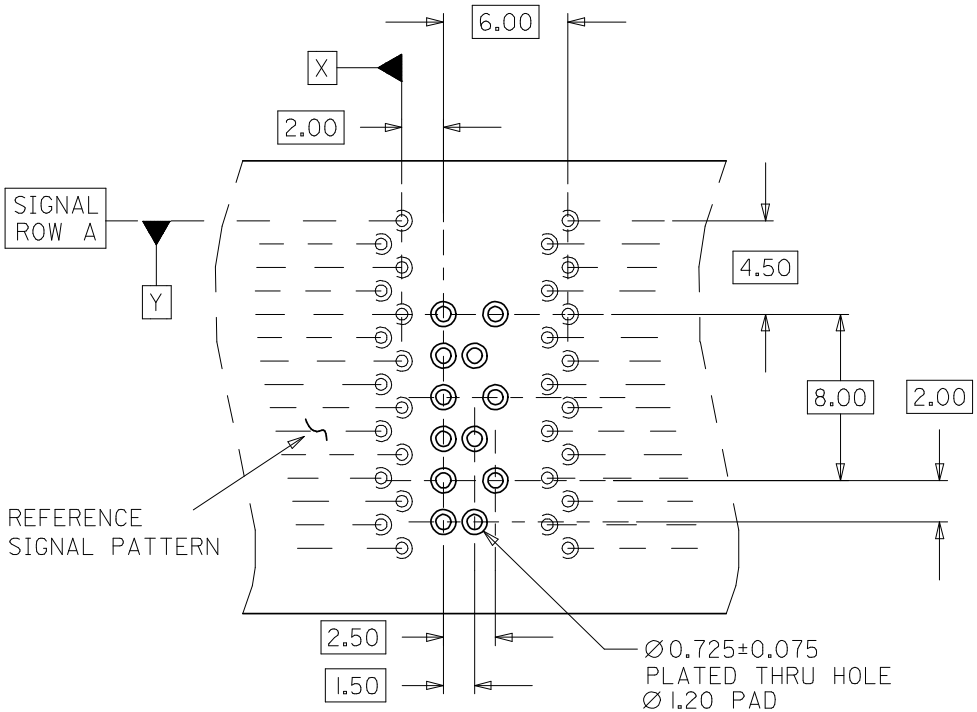
Packaging Specification	PK-70873-0876
Product Specification	PS-74031-999
Sales Drawing	SD-74029-002, SD-74029-009

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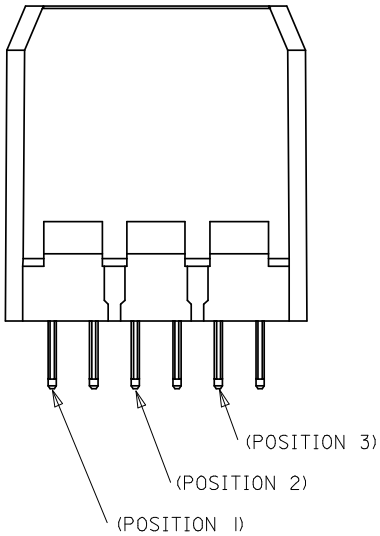




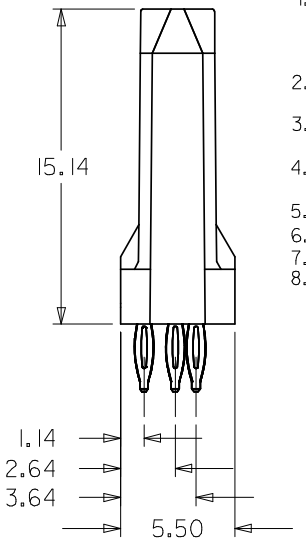




MIN. BOARD THICKNESS: 1.8 mm



SEE NOTE 8 & CHART



SEE NOTE 5

NOTES:

1. MATERIALS:
   HOUSING - LIQUID CRYSTAL POLYMER (LCP)
   UL94 V-0 RATED, COLOR: BLACK
   TERMINAL - COPPER ALLOY
2. FINISH: 30 microINCH MIN GOLD ON MATING SURFACE;
   TIN/LEAD ON TAILS; NICKEL OVERALL.
3. FINISH: 50 microINCH MIN GOLD ON MATING SURFACE;
   TIN/LEAD ON TAILS; NICKEL OVERALL.
4. THIS PART CONFORMS TO PRODUCT SPECIFICATION
   PS-74031-999.
5. USE 6.00 mm NOMINAL FOR BACKPLANE LAYOUT.
6. DIMENSION MEASURED FROM BOTTOM OF HOUSING.
7. PACKED PER PK-70873-0876.
8. CONTACT NOT PRESENT AT POSITION ON
   -84** ASSEMBLIES.

ASSEMBLY #	CONTACT PLATING	OPEN LOC.	# CONTACTS
74029-8000	SEE NOTE 2	N/A	3
74029-8050	SEE NOTE 3	N/A	
74029-8400	SEE NOTE 2	POS. 2	2
74029-8450	SEE NOTE 3	POS. 2	
74029-8401	SEE NOTE 2	POS. 1	
74029-8451	SEE NOTE 3	POS. 1	
74029-8403	SEE NOTE 2	POS. 3	
74029-8453	SEE NOTE 3	POS. 3	

REDRAWN
EC NO: UCP2008-1963 2008/02/18
DRWN: JBINGHAM 2008/02/18
CH'KD: JBINGHAM 2008/02/18
APPR: JLAURX 2008/02/18
DESCRIPTION
REV

QUALITY SYMBOLS
▼=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.15	± ---
1 PLACE	± 0.25	± ---
ANGULAR ±---°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NONE
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

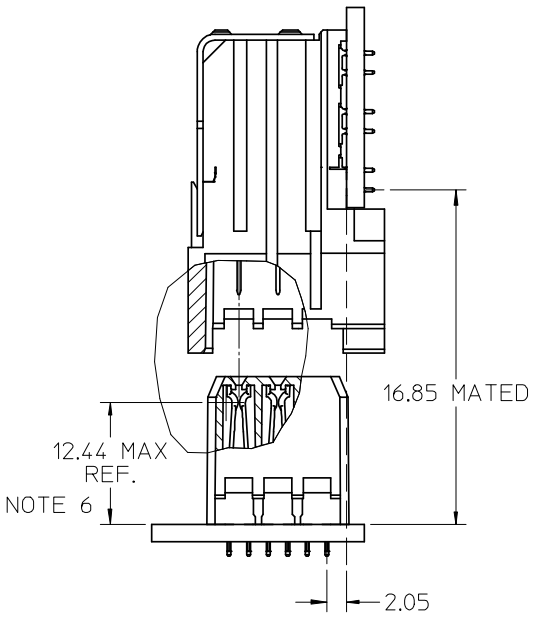
		DATE
DRAWN BY	TELO	98/10/19
CHECKED BY	DBREARLEY	98/10/21
APPROVED BY	CBIXLER	98/10/22

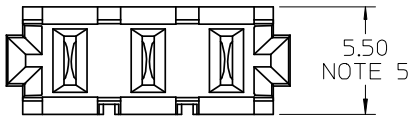
TITLE: VHDM POWER 8 ROW BACKPLANE SALES ASSEMBLY

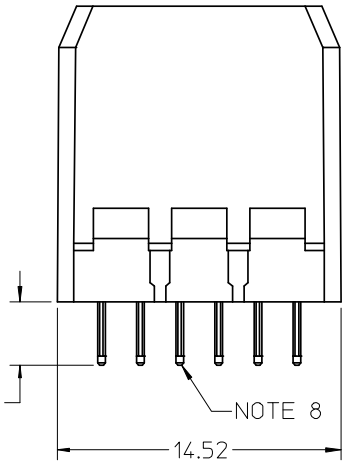
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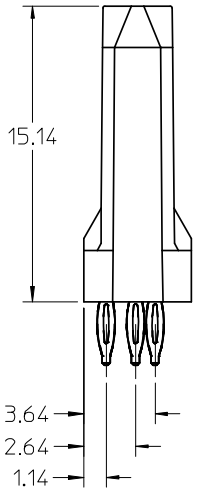
MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-74029-002
SHEET NO.: 1 OF 1
SIZE: B

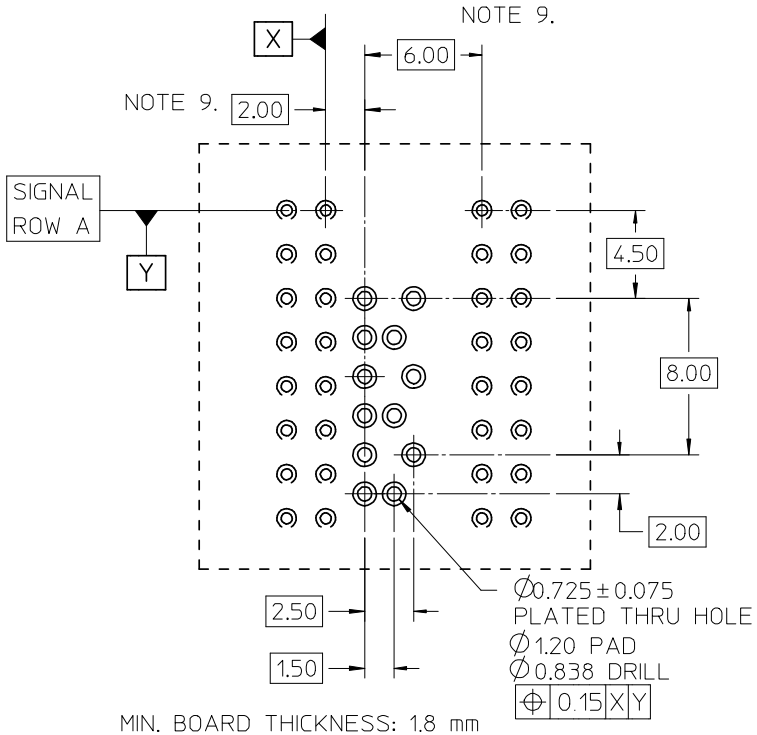
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NOTES:
1. MATERIALS:
   HOUSING - LIQUID CRYSTAL POLYMER (LCP)
   UL94 V-0 RATED, COLOR: BLACK
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2. FINISH: 30 microINCH MIN GOLD ON MATING SURFACE;
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3. FINISH: 50 microINCH MIN GOLD ON MATING SURFACE;
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4. THIS PART CONFORMS TO PRODUCT SPECIFICATION
   PS-74031-999.
5. USE 6.00 mm NOMINAL FOR BACKPLANE LAYOUT.
6. DIMENSION MEASURED FROM BOTTOM OF HOUSING.
7. PACKED PER PK-70873-0876.
8. MIDDLE CONTACT NOT PRESENT ON -84** ASSEMBLIES.
9. THIS DIMENSION TO BE MULTIPLE OF 2.00 mm AS REQUIRED.

ASSEMBLY #	CONTACT PLATING	# CONTACTS
74029-8000	SEE NOTE 2	3
74029-8050	SEE NOTE 3	3
74029-8400	SEE NOTE 2	2
74029-8450	SEE NOTE 3	2

REVISED (MINOR) EC NO: UCP2008-1963 DRWN: JBINGHAM 2008/02/18 CHKD: 2008/02/18 APPR: JLAURX 2008/02/18
DESCRIPTION
REV
A1

QUALITY SYMBOLS
▼ = 0
Ⓒ = 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.15	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

SCALE 4:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | REVISE ON CAD ONLY
DIMENSION STYLE MM ONLY
DRAWN BY ELO DATE 2001/10/04
CHECKED BY GORSKI DATE 2001/10/05
APPROVED BY BIXLER DATE 2001/10/08

TITLE
HSD POWER
8 ROW BACKPLANE
SALES ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO. SEE CHART | DOCUMENT NO. SD-74029-009 | SHEET NO. 1 OF 1

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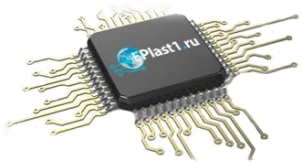
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- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Электронная почта: org@eplast1.ru
Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.